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INTERNATIONAL STANDARD



**Printed board assemblies –
Part 1: Generic specification – Requirements for soldered electrical and
electronic assemblies using surface mount and related assembly technologies**

INTERNATIONAL
ELECTROTECHNICAL
COMMISSION

ICS 31.190; 31.240

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CONTENTS

FOREWORD.....	7
1 Scope.....	9
2 Normative references.....	9
3 Terms and definitions	10
4 General requirements	11
4.1 Order of precedence	11
4.1.1 General remark	11
4.1.2 Conflict	11
4.1.3 Conformance documentation	12
4.2 Interpretation of requirements.....	12
4.3 Classification	12
4.4 Defects and process indicators	13
4.5 Process control requirements	13
4.6 Requirements flowdown	13
4.7 Physical designs	13
Design requirements	
4.7.1 New designs	13
4.7.2 Existing designs.....	13
4.8 Visual aids	14
4.9 Proficiency of personnel	14
4.9.1 Design proficiency.....	14
4.9.2 Manufacturing proficiency.....	14
4.10 Electrostatic discharge (ESD)	14
4.11 Facilities	14
4.11.1 General	14
4.11.2 Environmental controls.....	14
4.11.3 Temperature and humidity.....	15
4.11.4 Lighting	15
4.11.5 Field conditions.....	15
4.11.6 Clean rooms	15
4.12 Assembly tools and equipment	15
4.12.1 General	15
4.12.2 Process control	15
5 Requirements of materials	15
5.1 Overview.....	15
5.2 Solder.....	16
5.3 Flux	16
5.4 Solder paste	16
5.5 Preform solder	16
5.6 Adhesives	16
5.7 Cleaning agents	16
5.7.1 General	16
5.7.2 Cleaning agents selection	17
5.8 Polymeric coatings	17
General	
5.8.1 Solder resists and localized maskants	17

5.8.2	Conformal coating and encapsulants	17
5.8.3	Spacers (permanent and temporary).....	17
5.9	Chemical strippers	17
5.10	Cleaning Agents.....	17
5.11	Heat shrinkable soldering devices	17
6	Components and printed board requirements	18
6.1	General.....	18
6.2	Solderability	18
6.2.1	Parts solderability	18
6.2.2	Reconditioning	18
6.2.3	Solderability testing of ceramic boards	18
6.3	Solderability maintenance	18
6.3.1	General	18
6.3.2	Preconditioning	18
6.3.3	Gold embrittlement of solder joints	19
6.3.4	Tinning of non-solderable parts	19
6.4	Solder purity maintenance	19
6.5	Lead preparation	20
6.5.1	General	20
6.5.2	Lead forming.....	20
6.5.3	Lead-forming limits.....	21
7	Assembly process requirements.....	21
7.1	Overview.....	21
7.2	Cleanliness	21
7.3	Part markings and reference designations	21
7.4	Solder connection contours	21
7.5	Moisture traps.....	21
7.6	Thermal dissipation	21
8	Assembly soldering requirements.....	22
8.1	General.....	22
8.1.1	Soldering process	22
8.1.2	Machine maintenance	22
8.1.3	Handling of parts.....	22
8.1.4	Preheating	22
8.1.5	Carriers	22
8.1.6	Hold down of surface mount leads	22
8.1.7	Heat application	22
8.1.8	Cooling	23
8.2	Reflow soldering	23
8.2.1	Requirements	23
8.2.2	Process development for reflow soldering.....	23
8.2.3	Flux application.....	23
8.2.4	Solder application	23
8.3	Manual/hand soldering	24
8.3.1	Non-reflow manual soldering	26
8.3.2	Reflow manual soldering	26
	Mechanized immersion soldering (non-reflow).....	
	General	
	Process development for mechanized immersion soldering	

	Drying/degassing	
	Holding fixtures and materials	
	Flux application	
	Solder bath	
9	Cleanliness and residue requirements	27
9.1	General	27
	Equipment and material compatibility	
	Pre-soldering cleaning	
	Post-soldering cleaning	
	General	
	Ultrasonic cleaning	
	Cleanliness verification	
	General	
	Visual inspection	
	Testing	
	Cleanliness criteria	
	General	
	Particulate matter	
	Flux residues and other ionic or organic contaminants	
	Cleaning option	
	Test for cleanliness	
	Resin residues on cleaned board assemblies	
	Ionic residues (instrument method)	
	Ionic residues (manual method)	
	Surface insulation resistance (SIR)	
	Other contamination	
9.2	Qualified cleaning/manufacturing process	30
9.2.1	General	30
9.2.2	Cleaning designator	31
9.2.3	Upper specification limit	31
9.3	Visual requirements	31
9.4	Correlation of ionic testers	32
9.5	Non-ionic residues	32
9.6	SIR testing	32
10	Assembly requirements	27
10.1	General	32
10.2	Acceptance requirements	32
10.2.1	Process control	32
10.2.2	Corrective action limits	33
10.2.3	Control limit determination	33
10.3	General assembly requirements	33
10.3.1	Assembly integrity	33
10.3.2	Assembly damage	33
10.3.3	Markings	34
10.3.4	Flatness (bow and twist)	34
10.3.5	Solder connection	34
10.3.6	Interfacial connections	36
11	Coating and encapsulation	36
11.1	Conformal coating	36

11.1.1	Coating instructions	36
11.1.2	Application.....	36
11.1.3	Performance requirements	37
11.1.4	Rework of conformal coating	38
11.1.5	Conformal coating inspection	38
11.2	Encapsulation	38
11.2.1	Encapsulation instructions.....	38
11.2.2	Application.....	38
11.2.3	Performance requirements	39
11.2.4	Rework of encapsulant material.....	39
11.2.5	Encapsulant inspection	39
12	Rework and repair	39
General.....		
12.1	Rework of unsatisfactorily soldered electrical and electronic assemblies	39
12.2	Repair.....	40
12.3	Post rework/repair cleaning	40
13	Product quality assurance	41
13.1	System requirements.....	41
13.2	Inspection methodology.....	41
13.2.1	Verification inspection	41
13.2.2	Visual inspection.....	41
13.2.3	Sampling inspection	42
13.3	Process control	42
13.3.1	System details	42
13.3.2	Defect reduction.....	42
13.3.3	Variance reduction	43
14	Other requirements.....	43
14.1	Health and safety	43
14.2	Special manufacturing requirements	43
14.2.1	Manufacture of devices incorporating magnetic windings	43
14.2.2	High-frequency applications	43
14.2.3	High-voltage or high-power applications	43
14.3	Guidance on requirement flowdown	43
15	Ordering data	44
Annex A (normative) Requirements for soldering tools and equipment		45
A.1	Requirements for tools and equipment.....	45
A.2	Abrasives.....	45
A.3	Benchtop and hand-soldering systems.....	45
A.4	Soldering iron holders	46
A.5	Wiping pads	46
A.6	Soldering guns	46
A.7	Solder pots	46
A.8	Process control	46
Annex (normative) Qualification of fluxes.....		
Annex B (normative) Quality assessment		48
B.1	Process control (PC)	48
B.2	Reduction of quality conformance testing.....	48
B.3	Audit plan	49

Bibliography	50
Figure 1 – Solder contact angle.....	35
Figure 2 – Solder wetting of plated through-holes without leads	35
Figure 3 – Coating conditions.....	37
Table 1 – Solder contamination limits; maximum contaminant limit (percentage by weight)	19
Table 2 – Designation of surfaces to be cleaned.....	25
Table 3 – Residue testing for process control	25
Table 4 – Maximum acceptable rosin flux residues	26
Table 5 – Electrical and electronic assembly defects	34
Table 6 – Magnification requirements	35

INTERNATIONAL ELECTROTECHNICAL COMMISSION

PRINTED BOARD ASSEMBLIES –

**Part 1: Generic specification –
Requirements for soldered electrical and electronic assemblies
using surface mount and related assembly technologies**

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International Standard IEC 61191-1 has been prepared by IEC technical committee 91: Electronics assembly technology.

This third edition cancels and replaces the second edition published in 2013. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) the requirements have been updated to be compliant with the acceptance criteria in IPC-A-610F;
- b) the term "assembly drawing" has been changed to "assembly documentation" throughout;
- c) references to IEC standards have been corrected;
- d) Clause 9 was completely rewritten;
- e) Annex B was removed because there are already procedures for circuit board assemblies.

The text of this International Standard is based on the following documents:

CDV	Report on voting
91/1481/CDV	91/1510/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of IEC 61191 series, published under the general title *Printed board assemblies*, can be found in the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
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PRINTED BOARD ASSEMBLIES –

Part 1: Generic specification – Requirements for soldered electrical and electronic assemblies using surface mount and related assembly technologies

1 Scope

This part of IEC 61191 prescribes requirements for materials, methods and verification criteria for producing quality soldered interconnections and assemblies using surface mount and related assembly technologies. This part of IEC 61191 also includes recommendations for good manufacturing processes.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-2-20, *Environmental testing – Part 2-20: Tests – Test T: Test methods for solderability and resistance to soldering heat of devices with leads*

IEC 60068-2-58, *Environmental testing – Part 2-58: Tests – Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)*

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 60721-3-1, *Classification of environmental conditions – Part 3: Classification of groups of environmental parameters and their severities – ~~Section 1: Storage~~*

~~IEC 61188-1-1, *Printed boards and printed board assemblies – Design and use – Part 1-1: Generic requirements – Flatness considerations for electronic assemblies*~~

IEC 61189-1, *Test methods for electrical materials, interconnection structures and assemblies – Part 1: General test methods and methodology*

IEC 61189-3, *Test methods for electrical materials, printed boards and other interconnection structures and assemblies – Part 3: Test methods for interconnection structures (printed boards)*

IEC 61190-1-1, *Attachment materials for electronic assembly – Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly*

~~IEC 61190-1-2, *Attachment materials for electronic assembly – Part 1-2: Requirements for soldering pastes for high-quality interconnects in electronics assembly*~~

IEC 61190-1-3, *Attachment materials for electronic assembly – Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications*

IEC 61191-2, *Printed board assemblies – Part 2: Sectional specification – Requirements for surface mount soldered assemblies*

IEC 61191-3, *Printed board assemblies – Part 3: Sectional specification – Requirements for through-hole mount soldered assemblies*

IEC 61191-4, *Printed board assemblies – Part 4: Sectional specification – Requirements for terminal soldered assemblies*

IEC 61249-8-8, *Materials for interconnection structures – Part 8: Sectional specification set for non-conductive films and coatings – Section 8: Temporary polymer coatings*

IEC 61340-5-1, *Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements*

IEC/TR 61340-5-2, *Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena – User guide*

IEC 61760-2, *Surface mounting technology – Part 2: Transportation and storage conditions of surface mounting devices (SMD) – Application guide*

ISO 9001:2008, *Quality management systems – Requirements*

IPC-A-610E:2010, *Acceptability of Electronic Assemblies*

INTERNATIONAL STANDARD

NORME INTERNATIONALE

Printed board assemblies –

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Ensembles de cartes imprimées –

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CONTENTS

FOREWORD.....	6
1 Scope.....	8
2 Normative references.....	8
3 Terms and definitions	9
4 General requirements	10
4.1 Order of precedence	10
4.1.1 General remark	10
4.1.2 Conflict	10
4.1.3 Conformance documentation	10
4.2 Interpretation of requirements.....	11
4.3 Classification	11
4.4 Defects and process indicators	11
4.5 Process control requirements	12
4.6 Requirements flowdown	12
4.7 Physical designs	12
4.7.1 New designs	12
4.7.2 Existing designs.....	12
4.8 Visual aids	12
4.9 Proficiency of personnel	13
4.9.1 Design proficiency.....	13
4.9.2 Manufacturing proficiency.....	13
4.10 Electrostatic discharge (ESD).....	13
4.11 Facilities	13
4.11.1 General	13
4.11.2 Environmental controls.....	13
4.11.3 Temperature and humidity.....	13
4.11.4 Lighting	14
4.11.5 Field conditions.....	14
4.11.6 Clean rooms	14
4.12 Assembly tools and equipment	14
4.12.1 General	14
4.12.2 Process control	14
5 Requirements of materials	14
5.1 Overview.....	14
5.2 Solder.....	14
5.3 Flux	14
5.4 Solder paste	15
5.5 Preform solder	15
5.6 Adhesives	15
5.7 Cleaning agents	15
5.7.1 General	15
5.7.2 Cleaning agents selection	15
5.8 Polymeric coatings	16
5.8.1 Solder resists and localized maskants	16
5.8.2 Conformal coating and encapsulants	16
5.8.3 Spacers (permanent and temporary).....	16

5.9	Chemical strippers	16
5.10	Cleaning Agents.....	16
5.11	Heat shrinkable soldering devices	16
6	Components and printed board requirements	16
6.1	General.....	16
6.2	Solderability	17
6.2.1	Parts solderability	17
6.2.2	Reconditioning	17
6.2.3	Solderability testing of ceramic boards	17
6.3	Solderability maintenance	17
6.3.1	General	17
6.3.2	Preconditioning	17
6.3.3	Gold embrittlement of solder joints	17
6.3.4	Tinning of non-solderable parts	18
6.4	Solder purity maintenance	18
6.5	Lead preparation	19
6.5.1	General	19
6.5.2	Lead forming.....	19
6.5.3	Lead-forming limits.....	19
7	Assembly process requirements.....	20
7.1	Overview.....	20
7.2	Cleanliness	20
7.3	Part markings and reference designations	20
7.4	Solder connection contours	20
7.5	Moisture traps	20
7.6	Thermal dissipation	20
8	Assembly soldering requirements.....	20
8.1	General.....	20
8.1.1	Soldering process	20
8.1.2	Machine maintenance	21
8.1.3	Handling of parts.....	21
8.1.4	Preheating	21
8.1.5	Carriers	21
8.1.6	Hold down of surface mount leads	21
8.1.7	Heat application	21
8.1.8	Cooling	21
8.2	Reflow soldering	21
8.2.1	Requirements	21
8.2.2	Process development for reflow soldering.....	22
8.2.3	Flux application.....	22
8.2.4	Solder application	22
8.3	Manual/hand soldering	23
8.3.1	Non-reflow manual soldering	23
8.3.2	Reflow manual soldering	23
9	Cleanliness and residue requirements.....	24
9.1	General.....	24
9.2	Qualified cleaning/manufacturing process	24
9.2.1	General	24

9.2.2	Cleaning designator	25
9.2.3	Upper specification limit	25
9.3	Visual requirements	25
9.4	Correlation of ionic testers.....	26
9.5	Non-ionic residues	26
9.6	SIR testing	26
10	Assembly requirements.....	26
10.1	General.....	26
10.2	Acceptance requirements	26
10.2.1	Process control	26
10.2.2	Corrective action limits.....	27
10.2.3	Control limit determination.....	27
10.3	General assembly requirements	27
10.3.1	Assembly integrity.....	27
10.3.2	Assembly damage.....	27
10.3.3	Markings.....	28
10.3.4	Flatness (bow and twist).....	28
10.3.5	Solder connection	28
10.3.6	Interfacial connections	30
11	Coating and encapsulation.....	30
11.1	Conformal coating	30
11.1.1	Coating instructions	30
11.1.2	Application.....	30
11.1.3	Performance requirements	31
11.1.4	Rework of conformal coating	32
11.1.5	Conformal coating inspection	32
11.2	Encapsulation	32
11.2.1	Encapsulation instructions.....	32
11.2.2	Application.....	32
11.2.3	Performance requirements	33
11.2.4	Rework of encapsulant material.....	33
11.2.5	Encapsulant inspection	33
12	Rework and repair	33
12.1	Rework of unsatisfactorily soldered electrical and electronic assemblies	33
12.2	Repair.....	34
12.3	Post rework/repair cleaning	34
13	Product quality assurance.....	35
13.1	System requirements.....	35
13.2	Inspection methodology.....	35
13.2.1	Verification inspection	35
13.2.2	Visual inspection.....	35
13.2.3	Sampling inspection	36
13.3	Process control	36
13.3.1	System details	36
13.3.2	Defect reduction.....	36
13.3.3	Variance reduction	37
14	Other requirements.....	37
14.1	Health and safety	37

14.2	Special manufacturing requirements	37
14.2.1	Manufacture of devices incorporating magnetic windings	37
14.2.2	High-frequency applications	37
14.2.3	High-voltage or high-power applications	37
14.3	Guidance on requirement flowdown	37
15	Ordering data	37
Annex A	(normative) Requirements for soldering tools and equipment	39
A.1	Requirements for tools and equipment.....	39
A.2	Abrasives.....	39
A.3	Benchtop and hand-soldering systems.....	39
A.4	Soldering iron holders	40
A.5	Wiping pads	40
A.6	Soldering guns.....	40
A.7	Solder pots	40
A.8	Process control	40
Annex B	(normative) Quality assessment	41
B.1	Process control (PC)	41
B.2	Reduction of quality conformance testing.....	41
B.3	Audit plan	42
Bibliography		43
Figure 1	– Solder contact angle.....	29
Figure 2	– Solder wetting of plated through-holes without leads	30
Figure 3	– Coating conditions.....	31
Table 1	– Solder contamination limits; maximum contaminant limit (percentage by weight)	19
Table 2	– Designation of surfaces to be cleaned.....	25
Table 3	– Residue testing for process control	25
Table 4	– Maximum acceptable rosin flux residues	26
Table 5	– Electrical and electronic assembly defects	34
Table 6	– Magnification requirements	35

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IEC 61190-1-1, *Attachment materials for electronic assembly – Part 1-1: Requirements for soldering fluxes for high-quality interconnections in electronics assembly*

IEC 61190-1-3, *Attachment materials for electronic assembly – Part 1-3: Requirements for electronic grade solder alloys and fluxed and non-fluxed solid solders for electronic soldering applications*

IEC 61191-2, *Printed board assemblies – Part 2: Sectional specification – Requirements for surface mount soldered assemblies*

IEC 61191-3, *Printed board assemblies – Part 3: Sectional specification – Requirements for through-hole mount soldered assemblies*

IEC 61191-4, *Printed board assemblies – Part 4: Sectional specification – Requirements for terminal soldered assemblies*

IEC 61249-8-8, *Materials for interconnection structures – Part 8: Sectional specification set for non-conductive films and coatings – Section 8: Temporary polymer coatings*

IEC 61340-5-1, *Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements*

IEC/TR 61340-5-2, *Electrostatics – Part 5-2: Protection of electronic devices from electrostatic phenomena – User guide*

IEC 61760-2, *Surface mounting technology – Part 2: Transportation and storage conditions of surface mounting devices (SMD) – Application guide*

ISO 9001:2008, *Quality management systems – Requirements*

IPC-A-610, *Acceptability of Electronic Assemblies*

SOMMAIRE

AVANT-PROPOS.....	50
1 Domaine d'application.....	52
2 Références normatives	52
3 Termes et définitions	53
4 Exigences générales.....	54
4.1 Ordre de priorité.....	54
4.1.1 Remarque générale.....	54
4.1.2 Contradiction	54
4.1.3 Documentation relative à la conformité	55
4.2 Interprétation des exigences.....	55
4.3 Classification	55
4.4 Défauts et indicateurs de processus	56
4.5 Exigences relatives au contrôle du processus	56
4.6 Transmission des exigences.....	56
4.7 Conceptions physiques	56
4.7.1 Conceptions nouvelles	56
4.7.2 Conceptions existantes	57
4.8 Aides visuelles	57
4.9 Compétence du personnel.....	57
4.9.1 Compétence au niveau de la conception.....	57
4.9.2 Compétence au niveau de la fabrication	57
4.10 Décharge électrostatique (ESD, ElectroStatic Discharge).....	57
4.11 Installations	57
4.11.1 Généralités	57
4.11.2 Contrôles environnementaux	58
4.11.3 Température et humidité	58
4.11.4 Eclairage	58
4.11.5 Conditions sur le terrain	58
4.11.6 Salles blanches.....	58
4.12 Outils et matériel d'assemblage.....	58
4.12.1 Généralités	58
4.12.2 Contrôle de processus	58
5 Exigences relatives aux matériaux	59
5.1 Vue d'ensemble	59
5.2 Brasure.....	59
5.3 Flux	59
5.4 Pâte à braser	59
5.5 Préformes de brasage	59
5.6 Adhésifs.....	60
5.7 Agents nettoyants	60
5.7.1 Généralités	60
5.7.2 Choix des agents nettoyants	60
5.8 Revêtements en polymères	60
5.8.1 Epargnes de brasure et masques localisés	60
5.8.2 Revêtement enrobant et encapsulants	60
5.8.3 Ecarteurs (permanents et temporaires).....	60

5.9	Dénudeurs chimiques	61
5.10	Agents nettoyants	61
5.11	Dispositifs de brasage rétractables à la chaleur	61
6	Exigences relatives aux composants et cartes imprimées	61
6.1	Généralités	61
6.2	Brasabilité.....	61
6.2.1	Brasabilité des pièces	61
6.2.2	Reconditionnement	61
6.2.3	Essai de brasabilité des circuits sur substrats céramiques	61
6.3	Maintien de la brasabilité.....	62
6.3.1	Généralités	62
6.3.2	Préconditionnement	62
6.3.3	Effritement de la dorure dans les joints brasés.....	62
6.3.4	Etamage des pièces non brasables	62
6.4	Maintien de la pureté de la brasure.....	63
6.5	Préparation des sorties	64
6.5.1	Généralités	64
6.5.2	Formation des sorties.....	64
6.5.3	Limites de formation des sorties	64
7	Exigences relatives au processus d'assemblage	64
7.1	Vue d'ensemble	64
7.2	Propreté.....	64
7.3	Marquages des pièces et désignations de référence	64
7.4	Contours des connexions de brasure	65
7.5	Pièges à humidité	65
7.6	Dissipation thermique.....	65
8	Exigences relatives au brasage d'un ensemble.....	65
8.1	Généralités	65
8.1.1	Processus de brasure	65
8.1.2	Entretien de la machine.....	65
8.1.3	Manipulation des pièces	65
8.1.4	Préchauffage	65
8.1.5	Supports	65
8.1.6	Maintien en position basse des sorties de montage en surface.....	66
8.1.7	Application de chaleur.....	66
8.1.8	Refroidissement.....	66
8.2	Brasage par refusion	66
8.2.1	Exigences	66
8.2.2	Développement du processus pour le brasage par refusion.....	66
8.2.3	Application du flux.....	67
8.2.4	Application de la brasure.....	67
8.3	Brasage manuel.....	68
8.3.1	Brasage manuel sans refusion	68
8.3.2	Brasage manuel par refusion.....	68
9	Exigences relatives à la propreté et aux résidus	69
9.1	Généralités	69
9.2	Processus de nettoyage/fabrication qualifié	69
9.2.1	Généralités	69

9.2.2	Désignateur de propreté.....	70
9.2.3	Limite supérieure de spécification.....	70
9.3	Exigences visuelles.....	70
9.4	Corrélation des appareils d'essais ioniques	71
9.5	Résidus non ioniques	71
9.6	Essai de résistance d'isolement de surface.....	71
10	Exigences relatives à l'ensemble	71
10.1	Généralités	71
10.2	Exigences relatives à l'acceptation	72
10.2.1	Contrôle de processus	72
10.2.2	Limites de l'action corrective	72
10.2.3	Détermination de la limite de contrôle.....	72
10.3	Exigences générales relatives à l'ensemble.....	72
10.3.1	Intégrité de l'ensemble.....	72
10.3.2	Détérioration de l'ensemble.....	73
10.3.3	Marquage	73
10.3.4	Planéité (courbure et vrillage).....	73
10.3.5	Connexion brasée	73
10.3.6	Connexions d'interface.....	75
11	Revêtement et encapsulation	75
11.1	Revêtement enrobant.....	75
11.1.1	Instructions relatives au revêtement	75
11.1.2	Application.....	75
11.1.3	Exigences relatives aux performances.....	77
11.1.4	Retouche du revêtement enrobant.....	77
11.1.5	Examen du revêtement enrobant.....	77
11.2	Encapsulation	77
11.2.1	Instructions relatives à l'encapsulation.....	77
11.2.2	Application.....	78
11.2.3	Exigences relatives aux performances.....	78
11.2.4	Retouche du matériau encapsulant.....	78
11.2.5	Examen de l'encapsulant	78
12	Retouches et réparations	78
12.1	Retouche des ensembles électriques et électroniques brasés non satisfaisants.....	78
12.2	Réparations	79
12.3	Nettoyage après des retouches ou des réparations	79
13	Assurance de la qualité du produit	80
13.1	Exigences relatives au système.....	80
13.2	Méthodologie d'examen.....	80
13.2.1	Examen de vérification.....	80
13.2.2	Examen visuel	80
13.2.3	Examen par échantillonnage	81
13.3	Contrôle de processus.....	81
13.3.1	Détails relatifs au système	81
13.3.2	Réduction des défauts.....	82
13.3.3	Réduction de la variance	82
14	Autres exigences	82

14.1	Santé et sécurité	82
14.2	Exigences spéciales relatives à la fabrication	82
14.2.1	Fabrication de dispositifs comprenant des enroulements magnétiques	82
14.2.2	Applications à haute fréquence.....	82
14.2.3	Applications à haute tension et à puissance élevée.....	82
14.3	Recommandation sur la transmission des exigences	83
15	Données relatives aux commandes	83
Annex A	(normative) Exigences relatives aux outils et au matériel de brasage	84
A.1	Exigences relatives aux outils et au matériel.....	84
A.2	Abrasifs	84
A.3	Appareils de table et autres systèmes de brasage manuel	84
A.4	Supports de fer à braser.....	85
A.5	Tampons de nettoyage	85
A.6	Pistolets à braser	85
A.7	Pots de brasage.....	85
A.8	Contrôle de processus.....	85
Annex B	(normative) Evaluation de la qualité.....	86
B.1	Contrôle de processus.....	86
B.2	Réduction des essais de conformité de la qualité	86
B.3	Plan d'audit.....	87
Bibliographie		88
Figure 1	– Angle de contact de brasure	74
Figure 2	– Mouillage de brasure de trous traversants métallisés sans sorties	75
Figure 3	– Conditions de revêtement.....	76
Tableau 1	– Limites de contamination de la brasure; limite maximale de contamination (pourcentage en masse)	63
Tableau 2	– Désignation des surfaces à nettoyer.....	70
Tableau 3	– Essais sur les résidus pour le contrôle de processus	70
Tableau 4	– Niveau maximal autorisé de résidus de flux de résine	71
Tableau 5	– Défauts des ensembles électriques et électroniques	79
Tableau 6	– Exigences relatives au grossissement	80

COMMISSION ELECTROTECHNIQUE INTERNATIONALE

ENSEMBLES DE CARTES IMPRIMÉES –

Partie 1: Spécification générique – Exigences relatives aux ensembles électriques et électroniques brasés utilisant les techniques de montage en surface et associées

AVANT-PROPOS

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La Norme internationale IEC 61191-1 a été établie par le comité d'études 91 de l'IEC: Techniques d'assemblage des composants électroniques.

Cette troisième édition annule et remplace la deuxième édition parue en 2013. Cette édition constitue une révision technique.

Cette édition inclut les modifications techniques majeures suivantes par rapport à l'édition précédente:

- a) les exigences ont été mises à jour pour être conformes aux critères d'acceptation de l'IPC-A-610F;
- b) le terme "dessin d'assemblage" a été remplacé partout par "document d'assemblage";
- c) les références aux normes IEC ont été corrigées;

- d) l'Article 9 a été entièrement réécrit;
- e) l'Annexe B a été retirée car des procédures d'assemblages de cartes à circuits existent déjà.

Le texte de cette Norme internationale est issu des documents suivants:

CDV	Rapport de vote
91/1481/CDV	91/1510/RVC

Le rapport de vote indiqué dans le tableau ci-dessus donne toute information sur le vote ayant abouti à l'approbation de cette Norme internationale.

Ce document a été rédigé selon les Directives ISO/IEC, Partie 2.

Une liste de toutes les parties de la série IEC 61191, publiées sous le titre général *Ensembles de cartes imprimées*, peut être consultée sur le site web de l'IEC.

Le comité a décidé que le contenu de ce document ne sera pas modifié avant la date de stabilité indiquée sur le site web de l'IEC sous "<http://webstore.iec.ch>" dans les données relatives au document recherché. A cette date, le document sera

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ENSEMBLES DE CARTES IMPRIMÉES –

Partie 1: Spécification générique – Exigences relatives aux ensembles électriques et électroniques brasés utilisant les techniques de montage en surface et associées

1 Domaine d'application

La présente partie de l'IEC 61191 établit les exigences relatives aux matériaux, méthodes et critères de vérification utilisés dans le cadre de la production d'interconnexions et d'ensembles brasés de qualité faisant appel à la technique de montage en surface ainsi qu'à des techniques d'assemblage associées. La présente partie de l'IEC 61191 comprend également des recommandations concernant la qualité des processus de fabrication.

2 Références normatives

Les documents suivants cités dans le texte constituent, pour tout ou partie de leur contenu, des exigences du présent document. Pour les références datées, seule l'édition citée s'applique. Pour les références non datées, la dernière édition du document de référence s'applique (y compris les éventuels amendements).

IEC 60068-2-20, *Essais d'environnement – Partie 2-20: Essais – Essai T: Méthodes d'essai de la brasabilité et de la résistance à la chaleur de brasage des dispositifs à broches*

IEC 60068-2-58, *Essais d'environnement – Partie 2-58: Essais – Essai Td: Méthodes d'essai de la soudabilité, de la résistance de la métallisation à la dissolution et de la résistance à la chaleur de brasage des composants pour montage en surface (CMS)*

IEC 60194, *Conception, fabrication et assemblage des cartes imprimées – Termes et définitions*

IEC 60721-3-1, *Classification des conditions d'environnement – Partie 3: Classification des groupements des agents d'environnement et de leurs sévérités – Stockage*

IEC 61189-1, *Méthodes d'essai pour les matériaux électriques, les structures d'interconnexion et les ensembles – Partie 1: Méthodes d'essai générales et méthodologie*

IEC 61189-3, *Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles – Partie 3: Méthodes d'essai des structures d'interconnexion (cartes imprimées)*

IEC 61190-1-1, *Matériaux de fixation pour les assemblages électroniques – Partie 1-1: Exigences relatives aux flux de brasage pour les interconnexions de haute qualité dans les assemblages de composants électroniques*

IEC 61190-1-3, *Matériaux de fixation pour les assemblages électroniques – Partie 1-3: Exigences relatives aux alliages à braser de catégorie électronique et brasure solide fluxée et non-fluxée pour les applications de brasage électronique*

IEC 61191-2, *Ensembles de cartes imprimées – Partie 2: Spécification intermédiaire – Exigences relatives à l'assemblage par brasage pour montage en surface*

IEC 61191-3, *Ensembles de cartes imprimées – Partie 3: Spécification intermédiaire – Exigences relatives à l'assemblage par brasage de trous traversants*

IEC 61191-4, *Ensembles de cartes imprimées – Partie 4: Spécification intermédiaire – Exigences relatives à l'assemblage de bornes par brasage*

IEC 61249-8-8, *Matériaux pour les structures d'interconnexion – Partie 8: Collection de spécifications intermédiaires pour les films et revêtements non conducteurs – Section 8: Revêtements amovibles de polymères*

IEC 61340-5-1, *Electrostatique – Partie 5-1: Protection des dispositifs électroniques contre les phénomènes électrostatiques – Exigences générales*

IEC/TR 61340-5-2, *Electrostatique – Partie 5-2: Protection des dispositifs électroniques contre les phénomènes électrostatiques – Guide d'utilisation*

IEC 61760-2, *Technique du montage en surface – Partie 2: Transport et stockage des composants pour montage en surface (CMS) – Guide d'application*

ISO 9001:2008, *Systèmes de management de la qualité – Exigences*

IPC-A-610, *Acceptabilité des assemblages électroniques*